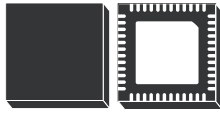
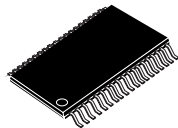


Octal industrial digital input current limiter with serialized output



QFN-48L 7.0 x 7.0 x 0.9 mm



HTSSOP-38 package

Product label



Product status link

[CLT01-38SQ7, CLT01-38S4](#)

Features

- Eight current-sinking digital inputs with serializer
- Enables inputs to meet type 1, 2 and 3 characteristic of IEC 61131-2 standard
- Adjustable and accurate input current limitation for low power and heat dissipation:
 - 2.35 mA typ for Type 1 and Type 3
- 35 V reverse polarity capable
- SPI-Compatible Serial Interface 8-bit
 - Optional 16-bit mode with parity check, and diagnostics (temperature alarm, voltage alarms)
- Daisy-Chain SPI to reduce isolation channels
- 5 V voltage regulator
- Energyless Field-Side LED drivers for visual status indication
- Operating ambient temperature range from -40 °C to 105 °C
- Packages
 - HTSSOP-38 – 500 µm pitch
 - QFN-48L – 500 µm pitch
- **Complies with the following standards:**
 - IEC 61000-4-2 level 4: ±15 kV (air discharge)
 - IEC 61000-4-2 level 4: ±8 kV (contact discharge)
 - IEC 61000-4-5 Surge ±1 kV /42 Ω with minimum 1 kΩ pulse resistor at field inputs

Applications

Where current limitation is required in [factory automation](#) applications:

- [Programmable logic controller](#)
- [Input modules](#)
- [CNC control](#)
- [Motor control](#)

Description

The CLT01 series is an octal industrial digital input IC, which drastically reduces the power dissipation of the digital input modules. Its current-sinking inputs can be configured for type 1, type 2, or type 3 inputs as per IEC 61131-2 with few external components.

The CLT01 series includes a serial interface, which translates, conditions, and serializes the data to CMOS-compatible signals through SPI. Combining its daisy-chaining capability with its accurate current limitation, the CLT01 series enhances the I/O module's density by cutting the power dissipation and reducing the number of optocouplers.

The CLT01 series can be evaluated thanks to the [STEVAL-IFP031V1](#) evaluation board. For detailed application guidelines, refer to the [AN4625](#).

1 Circuit block diagram

Figure 1. Circuit block diagram

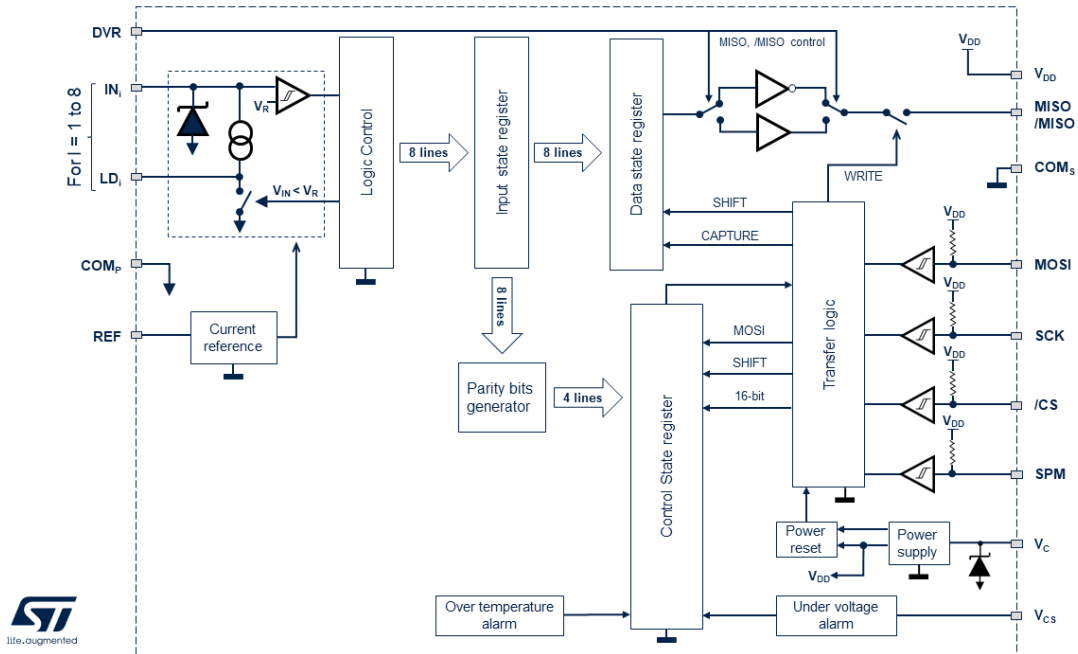
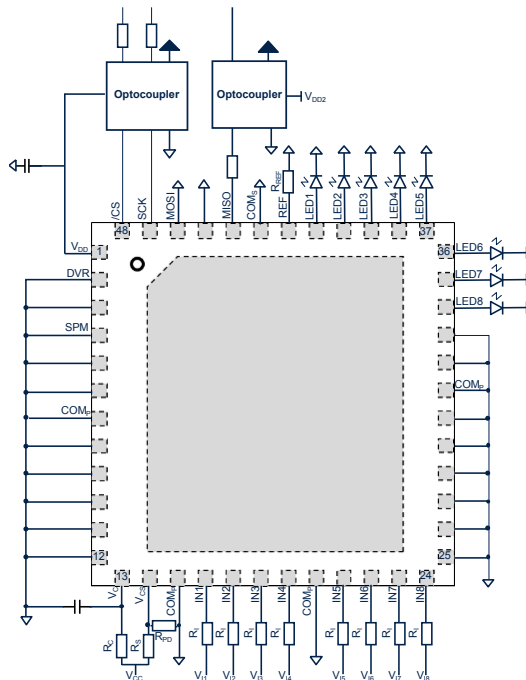


Figure 2. Typical application schematic



Note: In case of a LED not being used, the LED output pin must be connected to the ground COM_P to allow the input current to flow back to the ground.

1.1 I/O pin description

Table 1. I/O pin description

Symbol		Parameter	Pin # SCLT3-8BQ7	Pin # SCLT3-8BT8
IN _I	Power input	Logic input with current limitation, I = 1 to 8	16, 17, 18, 19, 21, 22, 23, 24	8 to 11, 13 to 16
LD _I	Power output	LED output driver with current regulation, I = 1 to 8	41, 40, 39, 38, 37, 36, 35, 34	27 to 20
V _C	Power input	24 V sensor power supply	13	5
V _{CS}	Signal input	24 V sensor power supply sensing input	14	6
COM _P	Ground	Power ground of power sensor supply	7, 15, 20, 31	4, 7, 12, 17
V _{DD}	Power output	5 V logic power supply	1	38
COM _S	Ground	Signal ground of logic / output section	43	30
REF	Signal input	Input current limiter reference setting	42	29
SPM	Signal input	SPI shift register length selector: <ul style="list-style-type: none"> • SPM to GND = 16 bits • SPM to V_{DD} = 8 bits 	4	3
/CS	Logic input	SPI chip select signal	48	35
SCK	Logic input	SPI serial clock signal	47	34
MOSI	Logic input	SPI serial data input signal	46	33
DVR	Logic input	Divider ratio selector of the digital input filters (8 or 64 steps)	2	1
MISO or / MISO	Logic output	SPI serial data output signal or inverting SPI serial data output signal	44	31
TAB	Substrate	Exposed pad to be connected to COM _P	TAB	Expose pad
NC		Not connected (or to be connected to COM _P)	5, 6, 8, 9, 10, 11, 12, 25, 26, 27, 28, 29, 30, 32, 33	2, 18, 19, 28, 32, 36, 37

Figure 3. Pinout description of the QFN-48L 7x7 and HTSSOP-38 versions (top view)

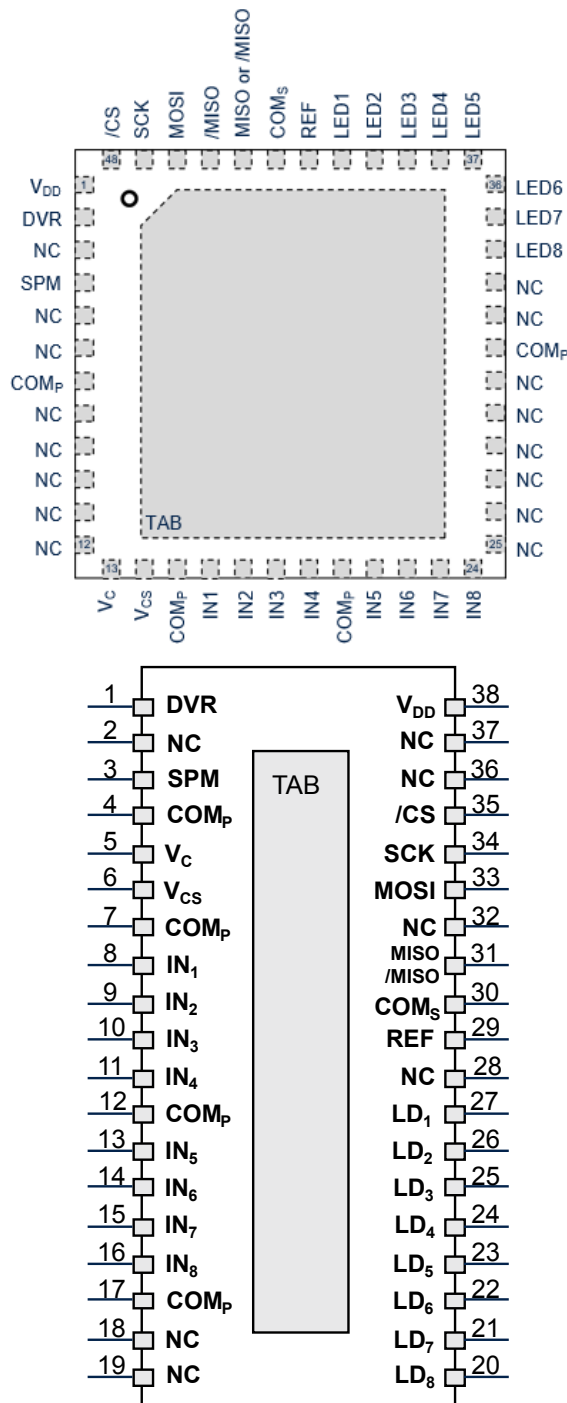
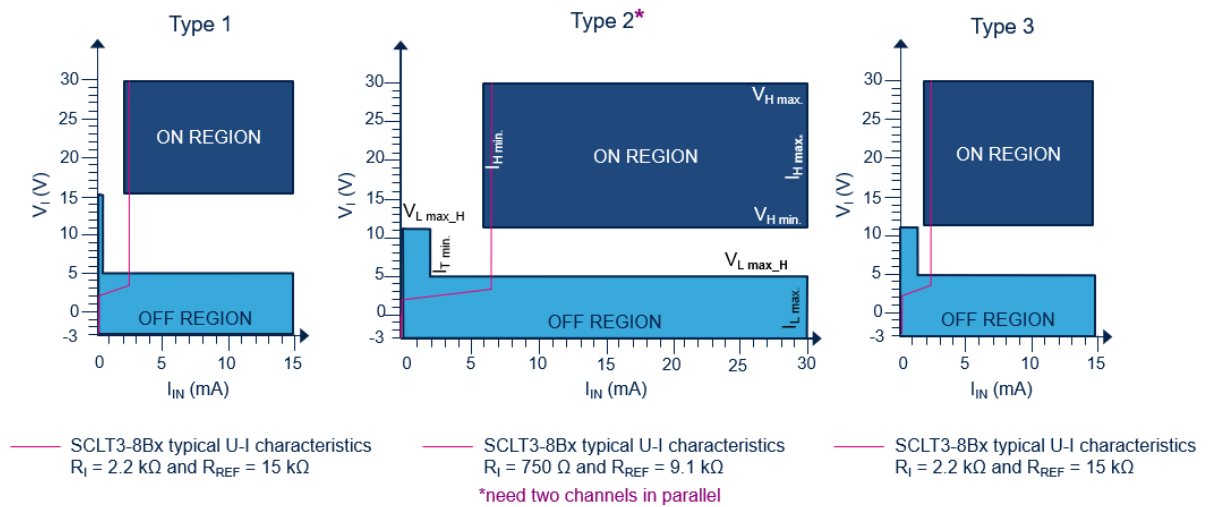


Figure 4. Switching characteristics for IEC61131-2 Type 1, 2, and 3 digital inputs (24 V DC)

Table 2. IEC61131-2 Input characteristic limits

Symbol ⁽¹⁾	Type 1	Type 2	Type 3
$U_{L \text{ max_H}}$	15 V	11 V	11 V
$U_{L \text{ max_L}}$	5 V	5 V	5 V
$I_{L \text{ max.}}$	15 mA	30 mA	15 mA
$I_{T \text{ min.}}$	0.5 mA	2 mA	1.5 mA
$U_{H \text{ min.}}$	15 V	11 V	11 V
$U_{H \text{ max.}}$	30 V	30 V	30 V
$I_{H \text{ min.}}$	2 mA	6 mA	2 mA
$I_{H \text{ max.}}$	15 mA	30 mA	15 mA

1. Symbol names are reported only on type 2 diagram for the sake of clarity.

2 Characteristics

Table 3. Absolute maximum ratings

Symbol	Pin	Parameter name	Conditions	Value	Unit
V _{CC}	V _C	Bus power supply DC voltage	500 Ω < R _C < 2.2 kΩ	-35 ⁽¹⁾ to 35 ⁽²⁾	V
V _C	V _C	Power supply voltage	R _C = 0 kΩ	-0.3 to 30	V
I _{CC}	V _C	Maximum bus power supply current		15	mA
V _{CS}	V _{CS}	Sensing bus power supply voltage		-0.3 to 6	V
I _{DD}	V _{DD}	Maximum output power supply current	R _C = 500 Ω	12	mA
V _I	IN _I	Input steady state voltage, I = 1 to 8	R _I = 2.2 kΩ	-35 to 35	V
I _{IN}	IN _I	Input forward current range		-20 to 10	mA
I _{OSC}	OSC	Maximum sourced oscillator current		120	μA
LV _I	SCK, /CS, MOSI	Logic input voltage		-0.3 to 6	V
T _{stg}		Storage temperature range		-40 to 150	°C
T _{amb}		Ambient temperature range		-40 to 105	°C

1. A reverse polarization diode must be placed on V_{CC} in order to avoid leakage when -35 V is applied.
2. 70 mm² of 35 μm thick copper is required for single layer FR4 PCB to have a low enough R_{th} and therefore keep CLT01-38Sx device below its T_{j(max)}.

Table 4. Electromagnetic compatibility ratings

Symbol	Pin	Parameter name	Value	Unit
V _{PPB}	IN _I	Peak pulse voltage burst, IEC 61000-4-4 ⁽¹⁾	4	kV
V _{PP}	IN _I	Peak pulse voltage surge, IEC 61000-4-5 (42 Ω), R _{IN} = 1 kΩ min ⁽²⁾	1	kV
V _{PP}	V _C	Peak pulse voltage surge, IEC 61000-4-5 (2 Ω), R _C = 2.2 kΩ ⁽²⁾	2.5	kV
V _{ESD}	IN _I	ESD protection, IEC 61000-4-2, per input, R _{IN} = 2.2 kΩ ⁽³⁾	15	kV
		Air discharge Contact discharge	8	

1. Refer to AN4625 for test setup and measurement results.
2. For R_{IN}, use a resistor able to withstand the surge (MELF resistor as example), else place bidirectional TVS between field input and GND with a low-power resistor in series for R_{IN}. Against 1 kV / 42 Ω 1.2 / 50 μs surges, recommended TVS are SPT02-236DDB or SMAJ33CA.
3. The package of the resistor should be large enough to prevent the arcing across the two resistor pads. Arcing depends on the ESD level applied to the field input and the application's pollution degree.

Note: For test set-up, see application in Figure 2.

Table 5. Operating conditions

Symbol	Pin	Parameter name	Conditions	Value	Unit
V _{CC}	V _C	Bus power supply DC voltage	R _C > 500 Ω	15 to 35 ⁽¹⁾	V
V _{DD}	V _{DD}	Internal logic power supply voltage		5	V
I _{DD}	V _{DD}	Internal logic power supply voltage	R _C > 500 Ω	10	mA
V _I	IN	Input repetitive steady state voltage	R _I = 2.2 kΩ ⁽²⁾	-30 to 35	V
V _{LD}	LD _X	Maximum LED output voltage, X = 1 to 8		2.7	V
F _{IN max.}	IN	Maximum single input frequency 8-bit mode		200	kHz
F _{SCK max.}		Maximum SPI clock frequency		6.25	MHz
LV	SCK, /CS, MOSI, MISO, /MISO	Logic input / output voltage		0 to 5.5	V
T _{amb}	All	Operating ambient temperature range	V _{CC} ≤ 30 V	-40 to 85	°C
T _j			V _{CC} ≤ 24 V, R _{th(j-a)} = 70 °C/W	-40 to 105	
		Operating junction temperature range		-40 to 150	°C

1. 32 V in DC; 35 V during 0.5 s max

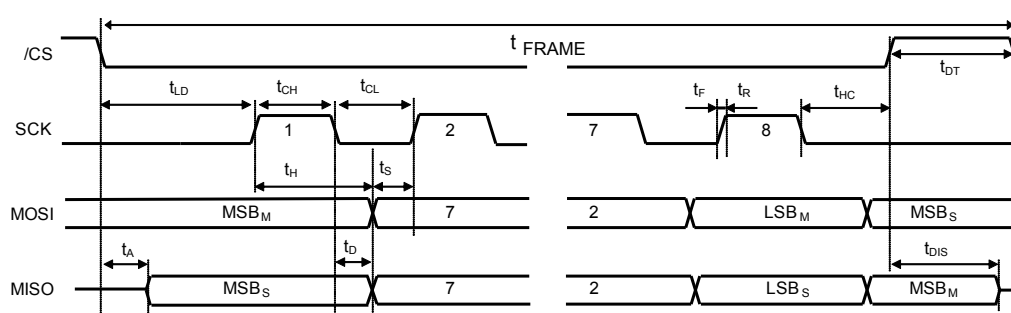
2. $V_I = V_{IN} + R_I \times I_{IN}$

Table 6. DC electrical characteristics based on figure 2 (T_{amb} = 25 °C, V_{CC} = 24 V, V_{DD} = 5 V respect to COM ground pin; unless otherwise specified)

Symbol	Pin	Name	Conditions	Min.	Typ.	Max.	Unit
Input current limitation							
I _{LIM}	IN _X	Input current limit	V _{IN} = 5.5 to 26 V, R _I = 2.2 kΩ	2.10	2.35	2.60	mA
I _{ON}	LD _X	On state LED current	V _I = 11 V	2			mA
V _{TLH}	IN _X	Input threshold Low-to-High	x = 1 to 8, R _I = 0 Ω		4.3		V
V _{THL}	IN _X	Input threshold High-to-Low	x = 1 to 8, R _I = 0 Ω		3.3		V
V _{THYST}	IN _X	Input threshold hysteresis	x = 1 to 8, R _I = 0 Ω		1.0		V

Table 7. SPI electrical characteristics ($T_{amb} = 25\text{ }^{\circ}\text{C}$, $V_{CC} = 24\text{ V}$, $V_{DD} = 5\text{ V}$ respect to COM ground pin; unless otherwise specified)

Symbol	Pin	Name	Conditions	Min.	Typ.	Max.	Unit
F_{CK}	SCK	Clock frequency				6.25	MHz
t_S	MOSI	Data setup time	MOSI toggling to SCK rising	25			ns
t_D	MISO	Write out propagation time	SCK falling to MISO toggling, $C_{OUT} = 10\text{ pF}$			50	ns
t_{LD}	SCK	Enable lead time	/CK falling to SCK rising	80			ns
t_{HC}	SCK	Clock hold time	SCK falling to /CS rising	160			ns
t_{DT}	/CS	Transfer delay time	/CS rising to /CS falling			150	ns
t_H	MOSI	Data hold time	SCK rising to MOSI toggling	25			ns
t_{DIS}	MISO	Data output disable time	/CS rising to MISO disabled			200	ns
LV_{IH}	MOSI, SCK, /CS	Logic input high voltage	Share of V_{DD}			70	%
LV_{IL}		Logic input low voltage	Share of V_{DD}	30			%
LV_{OH}	MISO, /MISO	Logic output high voltage	$I_{OH} = 3\text{ mA}$	4	4.75		V
LV_{OL}		Logic output low voltage	$I_{OL} = 3\text{ mA}$		0.25	1	V
t_{RO}, t_{FO}	MISO, /MISO	MISO signal fall/rise time	$I_{MISO} = 3\text{ mA}$		20		ns
t_A	MISO	Output access time	/CS falling to MISO toggling		40	80	ns
D_{UCY}	SCK	Clock duty cycle		25		75	%

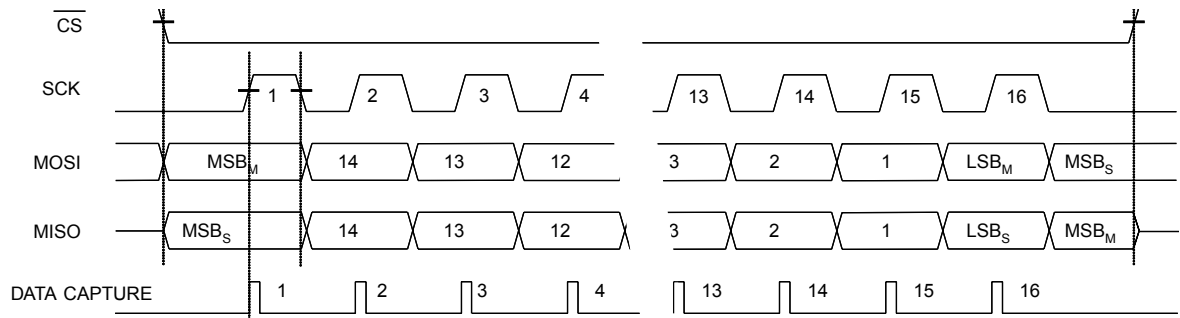
Figure 5. Time diagram


3 Functional description

3.1 Operation of the CLT01-38Sx with SPI bus ($C_{POL} = 0$, $C_{PHA} = 0$)

The SPI bus master controller manages the data transfer with the chip select signal /CS and controls the data shift in the register with the clock SCK signal.

Figure 6. Serial data format frame



The transfer of the CLT01-38Sx input states in the SPI registers starts when the chip select /CS signal falls and ends when this /CS is rising back.

The transfer of data out of the CLT01-38Sx slave MISO output starts immediately when the chip select /CS goes low.

Then, the input MOSI is captured and presented to the shift register on each rising edge of the clock SCK. And the data are shifted in this register on each falling edge of the serial clock SCK, the data bits being written on the output MISO with the most significant bit first.

3.1.1 The serial data Input MOSI

This input signal MOSI is used to shift external data bits into the CLT01-38Sx register from the most significant MSB bit to the lower significant one LSB. The data bits are captured by the CLT01-38Sx on the rising edge of the serial clock signal SCK.

3.2 The SPI data transfer operation

3.2.1 The SPI data frame

The selected structure of the SPI is a 16-bit word in order to be able to implement the input state data and some control bits such as the UVA alarm, the 4 checksum bits and the two low and high state stop bits.

Depending on the biasing of the SPM pin, the data frame is 8-bits or 16-bits. When SPM is grounded, 16 bits are transmitted - 8 input data bits and 8 control bits. When SPM is connected to V_{DD} , only the 8 input data bits are transmitted.

3.2.2 The SPI data transfer

The CLT01-38Sx transfers its 16 data bits through the SPI within one chip select Hi-Lo-Hi sequence. So, this length defines the minimum length that the shift register of the SPI master controller is able to capture: 16 bits. The Table 8. SPI data transfer organization versus CLT01-38Sx input states with SPM = 0 shows the 16-bit mode way the data are transferred starting from the data bits, the control bits and ending by a stop bit.

Table 8. SPI data transfer organization versus CLT01-38Sx input states with SPM = 0

Bit #	LSB	Bit 1	Bit 2	Bit 3	Bit 4	Bit 5	Bit 6	Bit 7
Control	High ⁽¹⁾	Low	PC4	PC3	PC2	PC1	/OTA	/UVA
Bit #	Bit 8	Bit 9	Bit 10	Bit 11	Bit 12	Bit 13	Bit 14	MSB
Data	IN 1	IN 2	IN 3	IN 4	IN 5	IN 6	IN 7	IN 8 ⁽²⁾

1. Last OUT
2. First OUT

3.3 Control bit signals of the SPI transferred data frame

3.3.1 The power bus voltage monitoring

The UVA circuit generates the alarm /UVA that is active low when the power bus voltage is lower than the activation threshold V_{CON} , 17 V typical, and it is disabled high when the power bus voltage rises above the threshold V_{COFF} , 18 V typical.

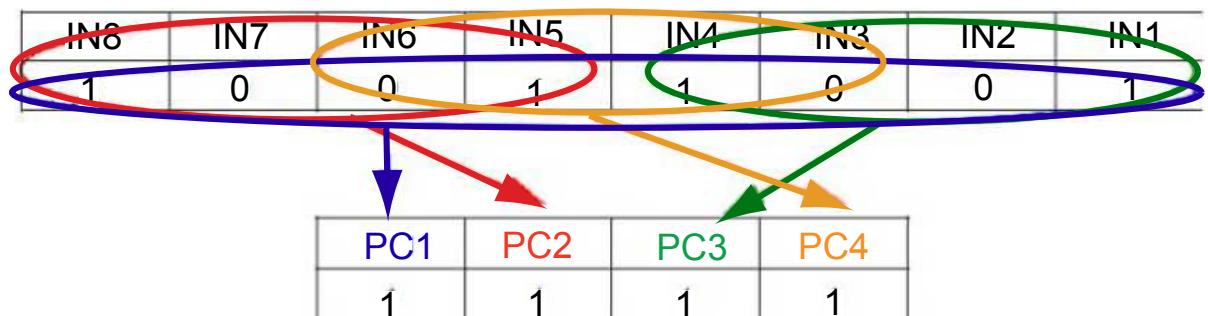
3.3.2 The over temperature alarm

The alarm signal /OTA is enabled, low state active, when the junction temperature is higher than the activation threshold T_{ON} , 150 °C typical, and it is disabled when the junction temperature falls below the threshold T_{OFF} , 140 °C typical.

3.3.3 The parity checksum bits calculation and transfer

The aim of the parity checksum bit is to detect one error in the transferred SPI word. Several parity checksum bits are generated and transmitted through the SPI on the control bit #2 to #5. In order to calculate parity bit, "exclusive NOR" operations are performed as follow:

Figure 7. SCLT3-8Bx parity bit calculation example



3.4 Loss of V_{CC} power supply

The operation of the CLT01-38Sx is extended below the levels required in the IEC 61131-2 standard to allow the implementation of the under voltage alarm UVA as described the SPI control bit section.

If there is no more power feeding on the V_{CC} input, the CLT01-38Sx chip goes to sleep mode, and the MISO output is forced in low state during SPI transfer attempt. The last SPI control data bit is a stop bit placed normally in high state all time: the loss of power supply is detected by checking its state: if low, the output is disabled by the internal power reset POR.

This POR signal is active in low state when V_C is less than 9 V or the internal power supply V_{DD} is less than 3.25 V.

Table 9. Logic state of the SPI output versus the power loss signal POR and the SPI chip select /CS

POR	/CS	MISO	/MISO	SPI status
1	1	Z	Z	Normal with no communication
1	0	1	0	Normal with communication
1	0	0	1	Normal with communication
0	1	Z	Z	Power loss with no communication
0	0	0	1	Power loss with communication attempt

Figure 8. Logic status of the CLT01-38Sx power supply

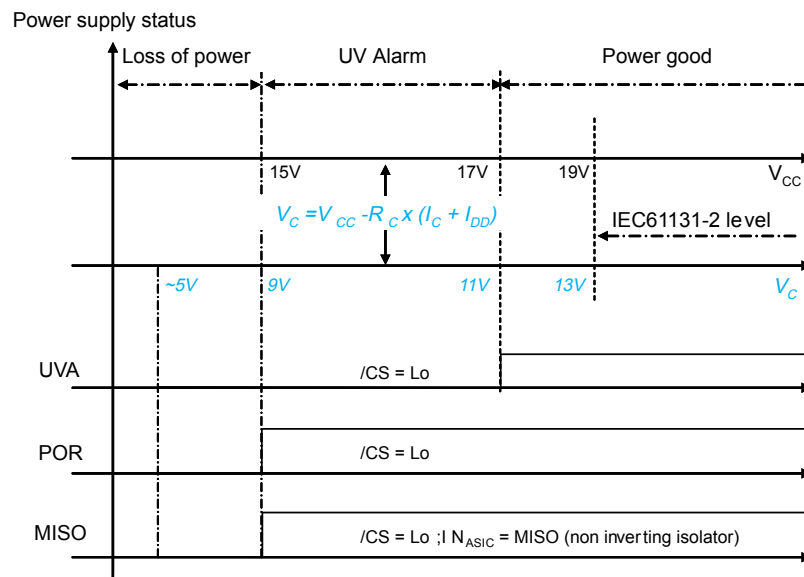
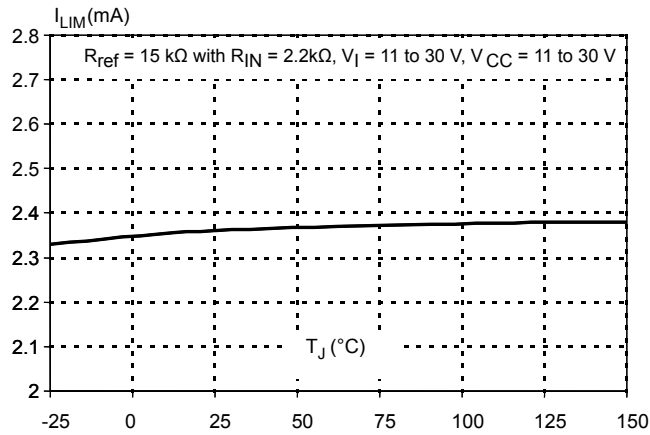


Figure 9. Typical limiting current I_{LIM} versus junction temperature T_J



3.5 Type 2 sensor inputs

The input current (6 mA min) of Type 2 input requires the use of two inputs of CLT01-38Sx in parallel. The current of each channel is set to 3.5 mA by setting R_{REF} to 9.1 k Ω . The effective current is then 7 mA nominal. The proper voltage drop across the input resistor is maintained by reducing the input resistance from 2.2 k Ω to 0.75 k Ω .

Figure 10. CLT01-38Sx - Type 2 input configuration

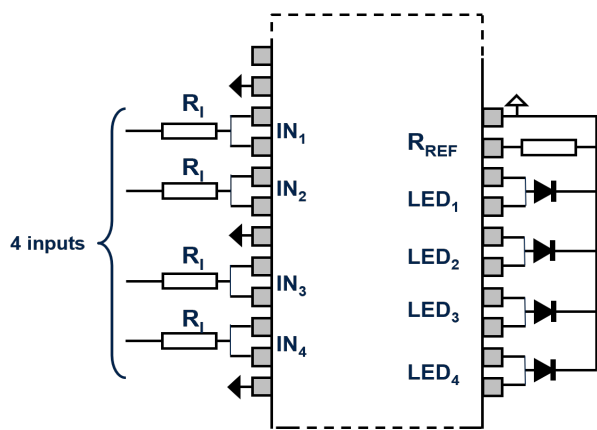
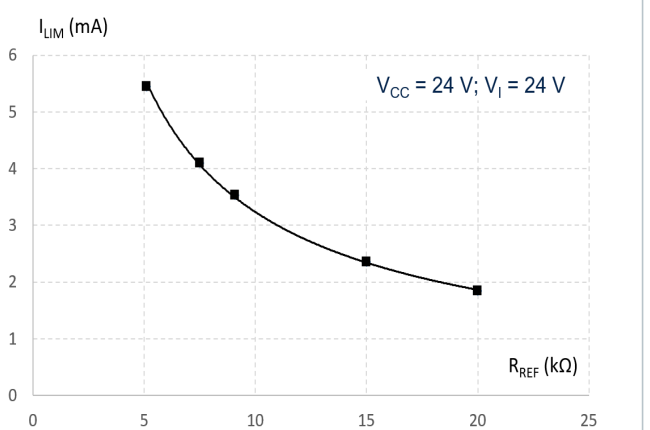


Figure 11. Typical limiting current I_{LIM} versus R_{REF}



Note: On the Figure 10. CLT01-38Sx - Type 2 input configuration for greater robustness against surges, place a 1.5 k Ω resistor on each channel and connect them in parallel to get equivalent resistance value of 0.75 k Ω .

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 QFN-48L 7.0 x 7.0 mm package information

Figure 12. QFN-48L 7.0 x 7.0 mm package outline

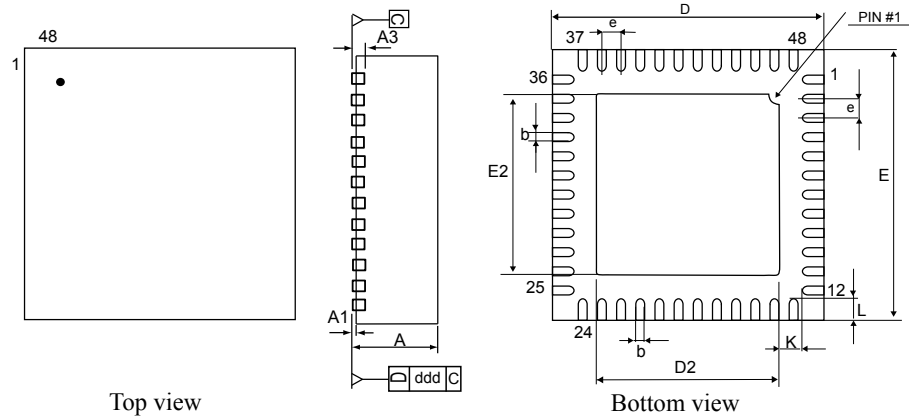


Table 10. QFN-48L 7.0 x 7.0 mm package mechanical data

Ref.	Dimensions					
	Millimeters			Inches ⁽¹⁾		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.80	0.90	1.00	0.0315	0.0354	0.0394
A1		0.02	0.05		0.0008	0.0020
A3		0.203			0.008	
b	0.18	0.25	0.30	0.0071	0.0100	0.0118
D		7.00			0.275	
E		7.00			0.275	
e		0.50			0.019	
D2	5.00	5.15	5.25	0.197	0.203	0.206
E2	5.00	5.15	5.25	0.197	0.203	0.206
K	0.20			0.008		
L	0.30	0.40	0.50	0.011	0.015	0.019

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 13. Footprint recommendations

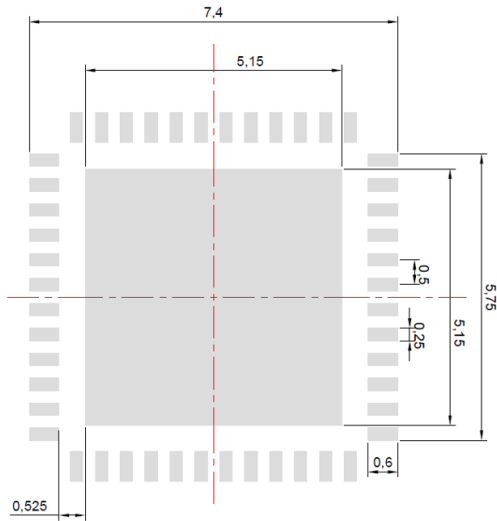
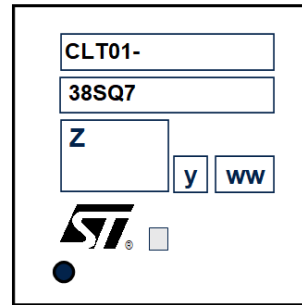


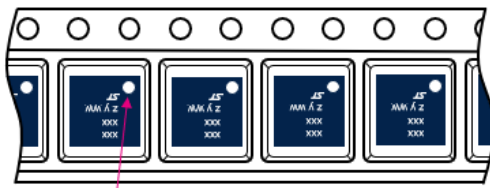
Figure 14. Marking



Dot indicates pin 1
ST logo
ECOPACK grade

Z = manufacturing location and traceability information
yww = datecode
y = year
ww = week

Figure 15. Package orientation in reel



Pin 1 located according to EIA-481

Note: Pocket dimensions are not on scale. Only pin 1 mark must be used to orient the component for its placement on a PCB.

Figure 16. Tape and reel orientation

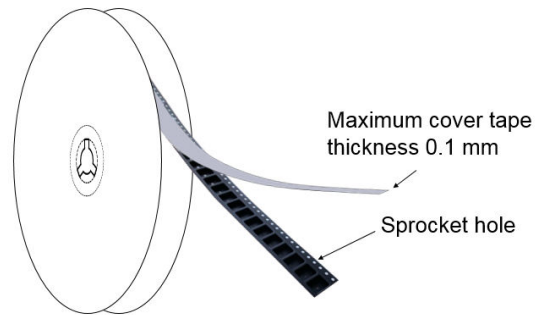


Figure 17. 13" reel dimensions values (mm)

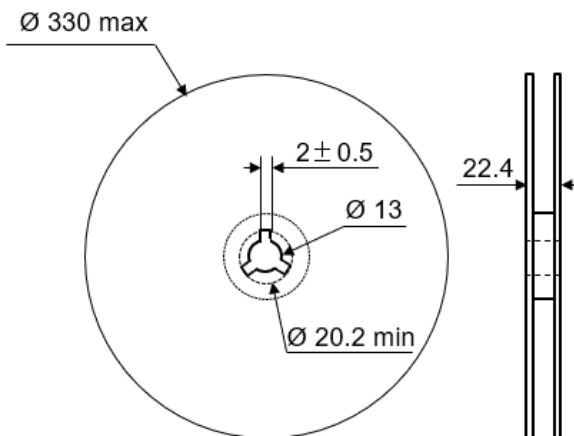


Figure 18. Inner box dimension values

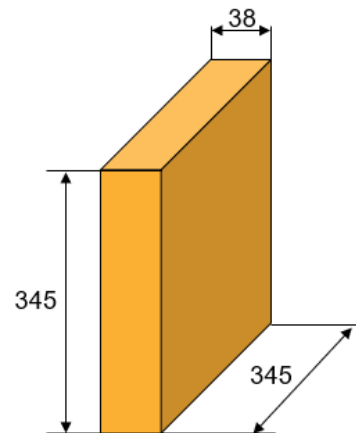
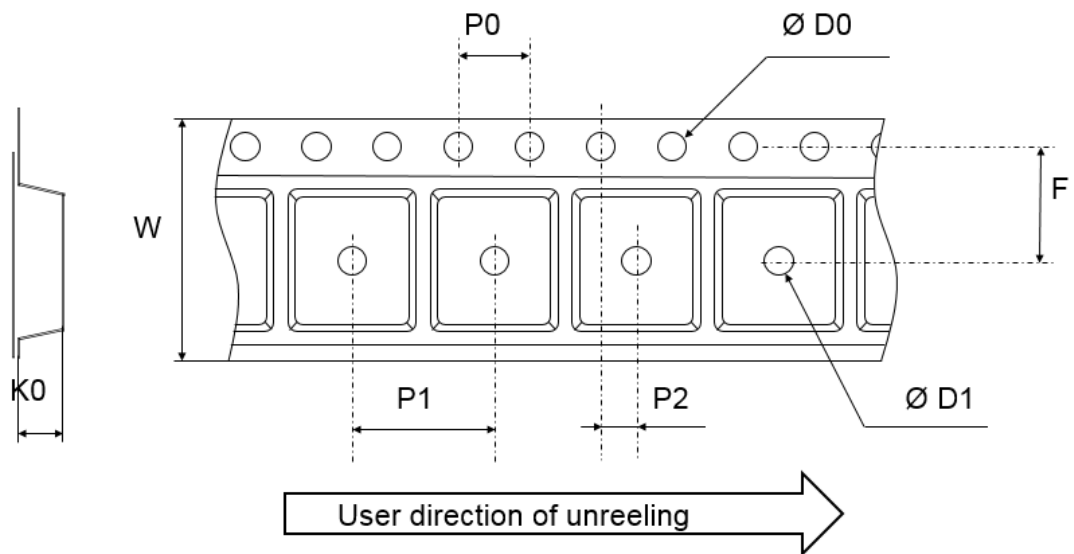


Figure 19. Tape outline



Note: Pocket dimensions are not on scale
Pocket shape may vary depending on package

Table 11. Tape dimension values

Ref.	Dimensions		
	Millimeters		
	Min.	Typ.	Max.
D0	1.50	1.55	1.60
D1	1.50		
F	7.40	7.50	7.60
K0	1.00	1.10	1.20
P0	3.90	4.00	4.10
P1	11.90	12.00	12.10
P2	1.90	2.00	2.10
W	15.70	16.00	16.30

4.2 HTSSOP-38 package information

Figure 20. HTSSOP-38 package outline

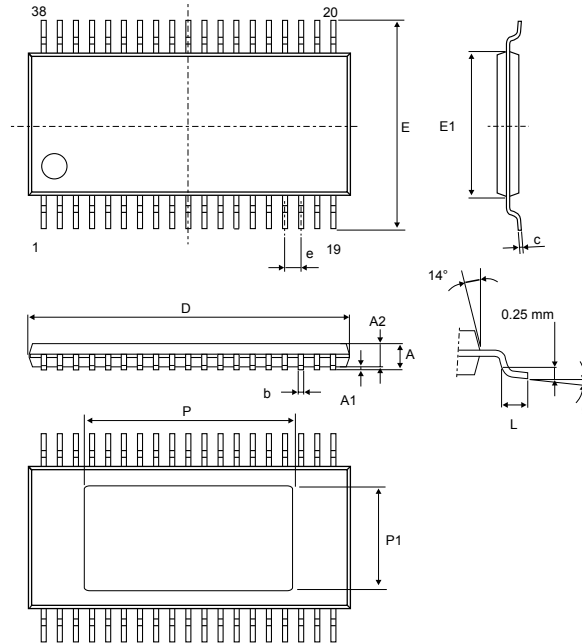


Table 12. HTSSOP-38 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches ⁽¹⁾		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.10			0.043
A1	0.05		0.15	0.002		0.006
A2	0.85	0.90	0.95	0.033	0.035	0.037
b	0.17		0.27	0.007		0.011
c	0.09		0.20	0.003		0.008
D	9.60	9.70	9.80	0.378	0.382	0.386
E1	4.30	4.40	4.50	0.169	0.173	0.177
e		0.50			0.020	
E		6.40			0.252	
L	0.50	0.60	0.70	0.020	0.024	0.027
P	6.40	6.50	6.60	0.252	0.256	0.260
P1	3.10	3.20	3.30	0.122	0.126	0.130
Ø	0°		8°	0°		8°

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 21. Footprint recommendations

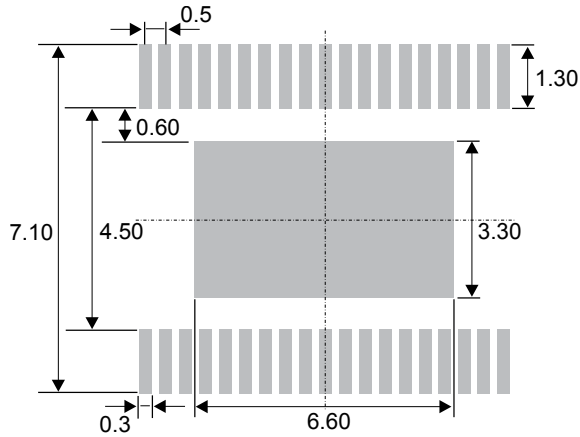
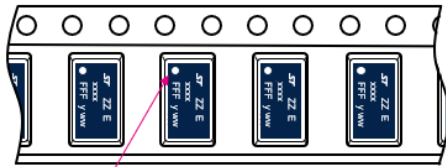


Figure 22. Marking



Dot indicates pin 1 Z = manufacturing location and traceability information
ST logo yww = datecode
□ ECOPACK grade y = year
E = eco level ww = week
F = traceability information

Figure 23. Package orientation in reel



Pin 1 located according to EIA-481

Note: Pocket dimensions are not on scale.
Only pin 1 mark must be used to orient the component for its placement on a PCB.

Figure 24. Tape and reel orientation

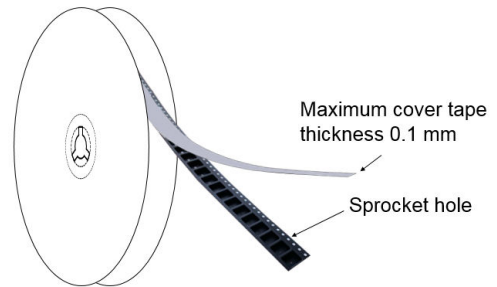


Figure 25. 13" reel dimensions values (mm)

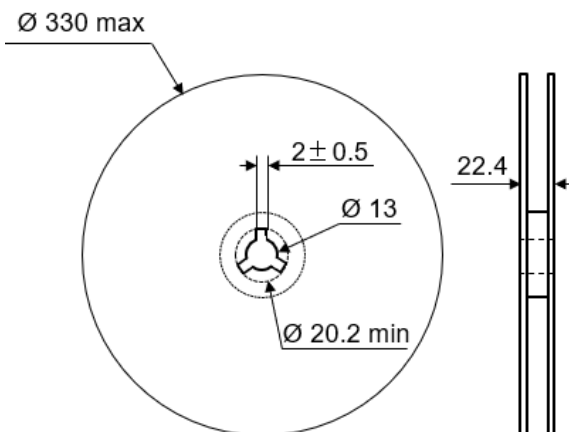


Figure 26. Inner box dimension values

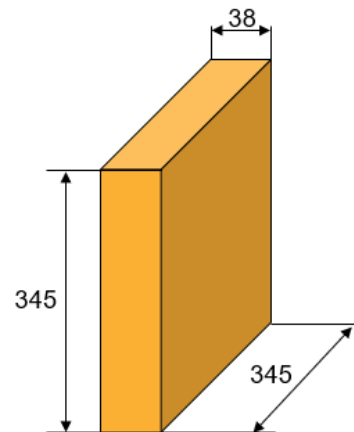
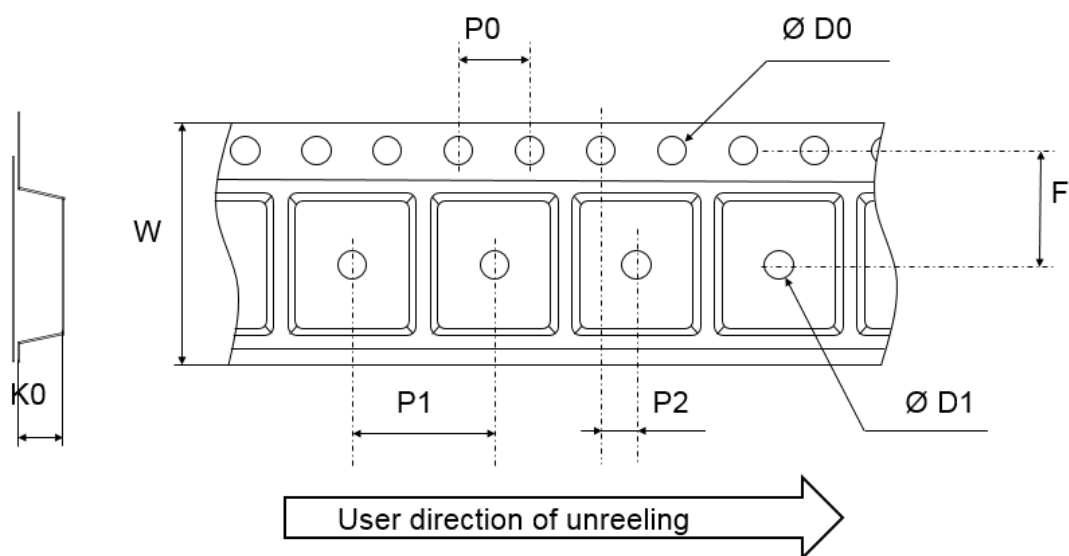


Figure 27. Tape outline



Note: Pocket dimensions are not on scale
Pocket shape may vary depending on package

Table 13. Tape dimension values

Ref.	Dimensions		
	Millimeters		
	Min.	Typ.	Max.
D0	1.50	1.55	1.60
D1	1.50		
F	7.40	7.50	7.60
K0	1.40	1.50	1.60
P0	3.90	4.00	4.10
P1	11.90	12.00	12.10
P2	1.90	2.00	2.10
W	15.70	16.00	16.30

5 Ordering information

Figure 28. Ordering information scheme

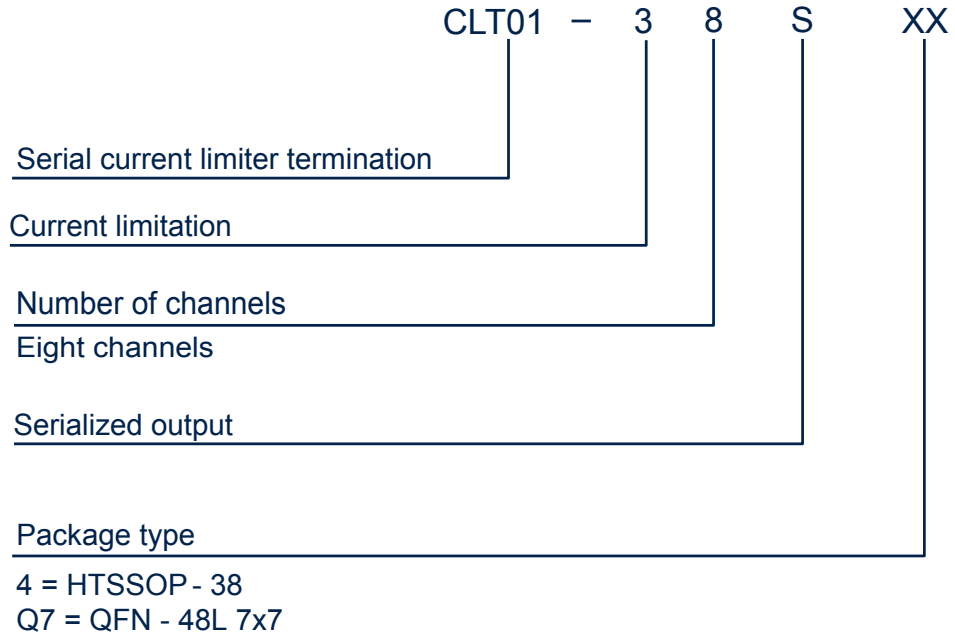


Table 14. Ordering information

Order code	Marking ⁽¹⁾	Package	Weight	Base qty.	Delivery mode
CLT01-38S4-TR	CLT01-38S4	HTSSOP-38	114 mg	2500	Tape and reel
CLT01-38S4	CLT01-38S4	HTSSOP-38	114 mg	50	Tube
CLT01-38SQ7-TR	CLT01-38SQ7	QFN-48L 7.0 x 7.0	130 mg	2500	Tape and reel

1. The marking can be rotated to differentiate assembly location.

Revision history

Table 15. Document revision history

Date	Revision	Changes
15-Sep-2023	1	Initial release.

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